

MICROELECTRONIC DEVICE PACKAGES AND METHODS FOR
CONTROLLING THE DISPOSITION OF NON-CONDUCTIVE MATERIALS IN
SUCH PACKAGES

ABSTRACT OF THE DISCLOSURE

A microelectronic package and method for forming such a package. In one embodiment, the package can include a microelectronic substrate having first connection sites, and a support member having second connection sites and third connection sites, with the third connection sites accessible for electrical coupling to other electrical structures. A plurality of electrically conductive couplers are connected between the first connection sites and the second connection sites, with neighboring conductive couplers being spaced apart to define at least one flow channel. The at least one flow channel is in fluid communication with a region external to the microelectronic substrate. The generally non-conductive material can be spaced apart from the support member to allow the microelectronic substrate to be separated from the support member.